

# DISTRIBUTORS OF SOLDERING MATERIAL & RELATED PRODUCTS

For the last 26 years, you have known us as your solder metals supplier, but now along with that, we bring to you a wide range of products from wave soldering machines to temperature-controlled soldering stations, ESD workplace products, heatsink compounds, and much more. Reasonable prices, timely delivery along with prompt and sound technical support are our specialties and our identity. We never want our customers to compromise on quality and provide only highly reliable products for our customers. We also provide training for shop floor operators, supervisors, and managers.













SOLDER WIRE



**SOLDER STICK** 



**SOLDER PASTE** 



**SOLDER FLUX** 

**BRAND:- BOND** 



**SOLDER WIRE** 

Fift

SAFFROHEAT 400

SPS TRADERS

**SAFFROHEAT 400** 



**SOLDER STICK** 



**SOLDER PASTE** 



**SOLDER FLUX** 

### **BRAND:- SRS TRADERS**



**SAFFROHEAT 401** 

**Heatsink Compound** 



SAFFROHEAT401 HTC

## BRAND:- SRS TRADERS



**SAFFROWAX** 

Wax Polish /
Wax Mold Release Agent

Silicone Dielectric

Grease



SAFFROLUB



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## SOLDER WIRE Non-RoHS(with lead) BRAND:- BOND



### 60/40 (Tin/Lead) NO CLEAN

**NON-ROHS** 

- No clean solder wire. No clean flux leaves no or very little residue after soldering
- Working temperature: 350to 380°C
- Flux percentage 0.9 to 1.5%
- Any guage as per customer need can be supplied
  - Joint has limited shining but excellent joint quality
    - Melting point: 183°C

#### **ROSIN CORED** 60/40 (Tin/Lead)

- Rosin cored or RMA flux which leaves brown sticky residue after soldering. You may or may not clean the PCB
- Solder joint has excellent shining and quality.
- Flux percentage:- 1.8% to 3%
- Any gauge as per customer need can be supplied
- This wire is especially used when component solderability is poor
- Melting point is 183°C

#### **NON-ROHS**





**NON-ROHS** 



- No clean flux. It leaves no or very little non-corrosive residue after soldering
- Excellent weting
- Working temperature: 325 to 375°C

#### **NON-ROHS**

#### **ROSIN CORED** 20/80(Tin/Lead)

- Melting point:- 183 to 280°c
- Especially used for capacitor soldering and bulb terminals soldering
- Flux percentage:- 1.8% to 3%
- Rosin or RMA





## SOLDER WIRE LEAD FREE BRAND:- BOND



#### LF3 99%Tin/0.3Silver/0.3%copper

**ROHS** 

- ROHS / Lead free compliant
- Melting point 227°C
- Working temperature 375 to 400°C
- No clean flux, leaving very less, clear & non-corrosive residue
- Flux percentage 0.9% to 1.5%
- Any gauge as per customer need can be supplied

#### **ROHS**

### LF9 99.3%Tin/0.7%copper

- ROHS or lead free compliant
- Melting point:- 227°C
- Working temperature:- 375 to 400°C
- No clean flux leaving no or less clear, non-corrosive residue
- Flux percentage 0.9% to 1.5%
- Any gauge as per customer need can be supplied





### LF2 96.5%Tin/3%Silver/0.5%Copper

**ROHS** 

- MELTING POINT :- 217 218C<sup>o</sup>
- WORKING TEMP (On tip): Should be 380 400 C<sup>o</sup>
- No clean flux leaving no or less clear and noncorrosive residue
- Flux percentage:- 2.50±0.20%
- Any gauge as per customers need can be supplied



## SOLDER STICK BRAND:- BOND



#### 63/37(Tin/Lead) LEADED

**NON-ROHS** 

- Eutectic solder
- Low surface tension in molten state
- Good wetting & flow, higher yeild rate
- Melting point:- 183°C
- Working temperature: 245 to 250°C
- Low Dross

#### **ROHS**

#### **LEAD FREE LF3**

- 99%Tin/0.3%Silver/0.7%Copper
- ROHS or Lead Free Compliant
- Low surface tension in molten state, low dross,
- Melting point 227°C
- Working temperature: 270°C ± 5°C





#### LF9 LEAD FREE

**ROHS** 

- 99.3%Tin/0.7%Copper
- ROHS or Lead free compliant
- Low surface tension in molten state, low dross
- Melting point 227°C
- Working temperature 250°C ± 5°C

#### **ROHS**

#### LEAD FREE LF2

- 96.5%Tin/3%Silver/0.5%Copper
- ROHS or Lead free compliant
- Low surface tension in molten state, low dross
- Melting point 217 to 221°C
- Working temperature 270°C ± 5°C





## SOLDER PASTE BRAND:- BOND



### 50/50(Tin/Lead ECO2

**NON-ROHS** 

- Economically priced, to be used for low end applications such as consumer electronics or LED manufacturing
- Available in T3 particle size
- Working temperature as per the reflow profile provided in datasheet

#### NON-ROHS 63/37(TIN/LEAD) T3/T4

- Available in both T3 & T4 particle size
- Excellent, homoginius & smooth applicability
- No soldering defects
- Working temperature as per the reflow profile provided in datasheet





#### LFA03 ROHS

- 99%Tin/0.3%Silver/0.7%Copper
- ROHS Compliant
- Stable & smooth continuous printing of high density electronics assemblies.
- Working temperature as per the reflow profile provided in the datasheet



## SOLDER FLUX BRAND:- BOND



#### **GQ/GK NIHON COSMO**

**NON-ROHS** 

- 63%Tin/37%Lead
- Available in both T3 & T4 particle sizes
- Excellent print ability & continuous printing performance
- Excellent solderability
- Working temperature as per reflow profile provided in the datasheet

#### **ROHS**

#### **NEHON GENMA**

- 99%Tin/ 0.3%Silver/0.7%Copper
- Excellent printability, solderability, and continuous printing performance
- Available in T4 particle size only
- Working temperature as per reflow profile provided in the datasheet





## SOLDERING FLUX BRAND:- BOND



#### 620DVD

**ROHS** 

- No clean soldering flux
- 2.50±0.5% solid content
- Low & clear, non-corrosive, hygroscopic residue.
- Excellent wetting and solderability
- Recommended for PTH boards

#### **ROHS**

#### **BOND NC 850L**

- No clean soldering flux
- 4.50±0.5% solid content
- Low & clear, non-corrosive, hygroscopic residue.
- Excellent wetting and solderability





#### **BOND NC 415**

ROHS

- No clean soldering flux
- 4.0 ± 0.5% solid content
- Low & clear, non-corrosive, non-hygroscopic residue.
- Excellent wetting and solderability
- Recommended for LED drive manufacturing

#### **ROHS**

### **BOND NC 620LP**

- No clean soldering flux
- 2.2 ± 0.2% solid content
- Low residue, excellent wettabilty, & solderability. Recommended for high density PTH boards
- Fast & consistent performance
- Low non-corrosive, non hygroscopic residue





# HEAT SINK COMPOUND BRAND:- SRS



#### **SAFFROHEAT 400**

- Thermal Conductivity:- 0.94W/mk
- Operating Temperature Range: -30°C to 240°C
- Colour:- Milky White
- Application:

Applied to the base and mounting studs of transistor, diodes and siliconecontrolled rectifiers, Power transistors, Diodes, semiconductors for effective Thermal Joints

#### **SAFFROHEAT 401**

- Thermal Conductivity:- 2.85 W/mk
- Operating Temperature Range: -30°C to 240°C
- Colour:- Blueish Grey
- Application:
- Applied to the base and mounting studs of transistor, diodes and siliconecontrolled rectifiers, Power transistors, Diodes, semiconductors for effective Thermal Joints





#### **SAFFROHEAT 401 HTC**

- Thermal Conductivity:- 3.39 W/mk
- Operating Temperature Range:- -30°C to 240°C
- Colour:- Grey
- Application:
- Applied to the base and mounting studs of transistor, diodes and siliconecontrolled rectifiers, Power transistors, Diodes, semiconductors for effective Thermal Joints



## DIELECTRIC SILICONE GREASE BRAND:- SRS



#### **SAFFROLUB 400**

- SAFE ON RUBBERS AND PLASTICS
- SILICONE GREASE THAT REPELS WATER AND PROTECTS AGAINST COROSION, ARCHING AND PITTING
- TEMPERATURE RANGE OF -50 TO 250°C (-58 TO 482°F)
- TEMPERATURE RESISTANT- DOES NOT HARDEN, MELT, BLEED, DRY, FREEZE, OR SEPARATE DUE TO TEMPERATURE FLUCTUATIONS.

#### **SAFFROLUB 500**

- SAFE ON RUBBERS AND PLASTICS
- SUITABLE FOR HIGH AND LOW VOLTAGE APPLICATIONS.
- TEMPERATURE RANGE OF -50 TO 250°C (-58 TO 482°F)
- TEMPERATURE RESISTANT- DOES NOT HARDEN, MELT, BLEED, DRY, FREEZE, OR SEPARATE DUE TO TEMPERATURE FLUCTUATIONS.



#### **WAX MOLD RELEASE AGENT**

#### **SAFFROWAX 400**



- USING AS A FIBERGLASS MOLD RELEASE AGENT, MOULDING WORK, FABRICATIONS, WOOD, AND FLOOR POLISHES.
- ENHANCE SURFACE PROPERTIES.
- EFFECTIVE MATTING AGENTS
- MOISTURE BARRIER AND GLOSSING AGENT.